PCB Manufacturing Technical Specifications

Seq	Item		Technical Specification	Remarks
			Imported	
1	Number of Layer		1-24 Layers	
2	Base Material		FR4, Teflon,Rogers,Aluminum Based	
3	Finish Board Thickness		0.13 mm - 4.5 mm (5 mil - 177 mil)	
4	Minimum Core Thickness		0.08mm (3 mil)	
5	Copper Thickness		Min. 1/4 OZ, Max. 6 OZ	Selective Area Available, Thicker Cu On Request
6	Min. Trace Wide& Line Space	Single Sided	0.08mm (3 mil)	
		Double Sided	0.08mm (3 mil)	
7	Min. Hole Diameter	Drilling /PTH	Dia0.10mm (4 mil)	
		Punching	Dia0.90 mm (36 mil)	
8	Dimension Tolerance	Hole Position	±0.05 (2 mil)	
		Conductor Width(W)	±1mil Deviation of Master A/W	
		Hole Diameter(H)	NPTH: ±0.03 mm (1 mil)	
			PTH: ±0.05 mm (2 mil)	
		Outline Dimension	±0.10 mm (4 mil)	
		Conductors & Outline (C - O)	±0.13 mm (5 mil)	
		Warp and Twist	0.50%	
9	Surface Treatment On Land Area		Hard Gold, Immersion Gold, Immersion Silver and HASL Leaded and Lead Free, Entek and Immersion Tin	
10	V-Cutting	Panel Size	457.2mm X 1200 mm (max.)	
		Board Thickness	0.30 mm (12mil) min.	
		Remain Thickness	0.40 +/-0.10mm (16+/-4 mil)	
		Tolerance	±0.1 mm(4mil)	
		Groove Width	0.38 mm (15mil) max.	
		Groove to Groove	10 mm (394mil) min.	
		Groove to Trace	0.38 mm(15mil) min.	
11	Slot	Slot size tol.L≥2W	PTH Slot: L : ±0.10(4mil) W : ±0.05(2mil)	(1)L=Length of slot (2)W=Width of slot (3)Min.drill bit size for multi-hit is 0.60mm
			NPTH slot(mm) L : ±0.08(3mil) W : ±0.05(2mil)	
12	Min Spacing from hole edge to hole edge	0.30-1.60 (Hole Diameter)	0.10mm(4mil)	
		1.61-6.50 (Hole Diameter)	0.13mm(5mil)	
13	Minimum spacing between hole edge to circuitry pattern		PTH hole: 0.13mm(5mil)	
			NPTH hole: 0.10mm(4mil)	
14	Image transferRegistration tolerance	Circuit pattern vs.index hole	±0.08(3mil)	
		Circuit patten vs. 2nd drill hole	±0.10(4mil)	
15	Registration tolerance of front/back image		0.05mm(2mil)	
16	Multilayers	Layer-layer misregistration	4layers: 0.10mm(4mil)max.	
			6layers: 0.13mm(5mil)max.	
			8layers: 0.15mm(6mil)max.	
			8-22 Layers 0.25mm(10mil)max.	
		Min.Spacing From Hole Edge to Innerlayer Pattern	0.15mm(6mil)	
		Min.Spacing From Outline to Innerlayer Pattern	0.225mm(9mil)	
		Min. board thickness	4layers:0.20mm(8mil)	
			6layers:0.50mm(20mil)	
			8layers:0.75mm(30mil)	
		Board thickness tolerance	4layers:+/-0.10mm(4mil)	
			6layers:+/-0.13mm(5mil)	
			8-12 layers:+/-0.15mm(6mil)	
			14-22 layers: +/-0.20mm (8mil)	
17	Insulation Resistance		10KΩ~20MΩ(typical:5MΩ)	
18	Conductivity		<50Ω(typical:25Ω)	
19	Test voltage		250V	
20	Impedance control		Typical: 50Ω+/-10%	